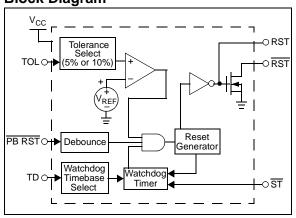


Microprocessor Monitor

Features:

- · Precision Voltage Monitor:
 - Adjustable +4.5V or +4.75V
- Reset Pulse Width 250 ms minimum
- · No External Components
- Adjustable Watchdog Timer:
 - 150 ms, 600 ms or 1.2s
- Operating Voltage 4.0V to 5.5V
- Debounced Manual Reset Input for External Override

Block Diagram



General Description:

The TC1232 is a fully-integrated processor supervisor that provides three important functions to safeguard processor sanity: precision power on/off Reset control, Watchdog Timer and external Reset override.

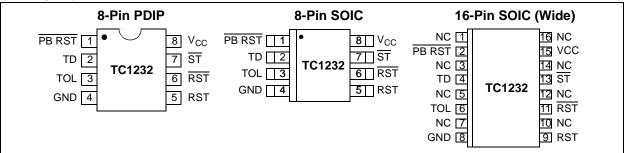
On power-up, the TC1232 holds the processor in the Reset state for a minimum of 250 ms after V_{CC} is within tolerance to ensure a stable system start-up.

Microprocessor sanity is monitored by the on-board watchdog circuit. The microprocessor must provide a periodic low-going signal on the \overline{ST} input. Should the processor fail to supply this signal within the selected time-out period (150 ms, 600 ms or 1200 ms), an out-of-control processor is indicated and the TC1232 issues a processor Reset as a result.

The outputs of the TC1232 are immediately driven active when the PB input is brought low by an external push button switch or other electronic signal. When connected to a push button switch, the TC1232 provides contact debounce.

The TC1232 is packaged in a space-saving 8-Pin PDIP or SOIC package, a 16-Pin SOIC (wide) package and requires no external components.

Package Types



Device Features

	R	ST pin		RST p	in	T. D	Minimum	WDI Input	
Device	Туре	Pull-up Resistor	Active Level	Туре	Active Level	Trip Points (Max)	Reset Active Time (ms)	Typical Timeouts (ms)	MR Input
TC1232	Open-drain	External	Low	Push-pull	High	4.75V or 4.5V	250	150, 600 or 1200	Yes

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Voltage on Any Pin (With Respect to GND)
.....-0.3V to +5.8V

Operating Temperature Range:

C-Version.......0°C to +70°C

E-Version....-40°C to +85°C

Storage Temperature Range: ...-65°C to +150°C

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $T_A = T_{MIN}$ to T_{MAX} ; $V_{CC} = +4.0V$ to 5.5V.							
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Supply Voltage	V _{CC}	4.0	5.0	5.5	V		
ST and PB RST Input High Level	V _{IH}	2.0	ı	V _{CC} +0.3	V	Note 1	
ST and PB RST Input Low Level	V_{IL}	-0.3		+0.8	V		
Input Leakage ST, TOL	ΙL	-1.0	_	+1.0	μA		
Output Current RST	I _{OH}	-1.0	-12	_	mA	V _{OH} = 2.4V	
Current RST, RST	I _{OL}	2.0	10	_	mA	V _{OL} = 0.4V	
Operating Current	I _{CC}		50	200	μΑ	Note 2	
V _{CC} 5% Trip Point	V _{CCTP}	4.50	4.62	4.74	V	TOL = GND (Note 3)	
V _{CC} 10% Trip Point	V _{CCTP}	4.25	4.37	4.49	V	TOL = V _{CC} (Note 3)	
Capacitance Electrical Characteristics: Unless otherwise noted, T _A = +25°C. (Note 4)							
Input Capacitance ST, TOL	C _{IN}	_	_	5	pF		
Output Capacitance RST, RST	C _{OUT}	_	_	7	pF		

- **Note 1:** PB RST is internally pulled up to V_{CC} with an internal impedance of typically 40 k Ω .
 - 2: Measured with outputs open.
 - 3: All voltages referenced to GND.
 - 4: Ensured by design.

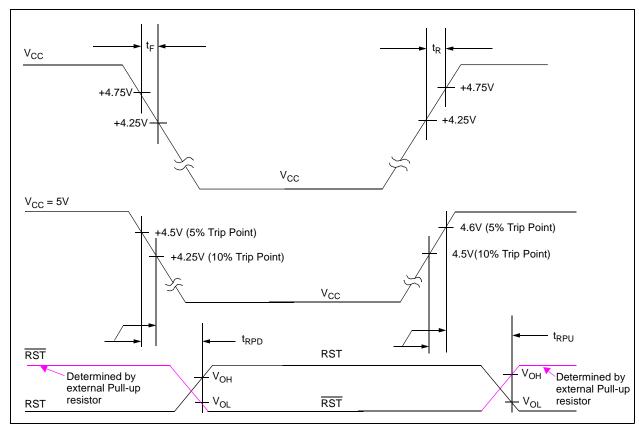


FIGURE 1-1: Rise Time, Fall Time and Reset Detected to Reset Active Timing Waveforms.

AC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $T_A = T_{MIN}$ to T_{MAX} ; $V_{CC} = +4.0V$ to 5.5V.						
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
V _{CC} Fall Time	t _F	10	_	_	μs	Note 1
V _{CC} Rise Time	t _R	0	_	_	μs	Note 1
V _{CC} Trip Point Detected to RST High and RST Low	t _{RPD}	_		100	ns	V _{CC} falling
V_{CC} Trip Point Detected to RST High and \overline{RST} Open	t _{RPU}	250	610	1000	ms	V _{CC} rising (Note 2)

Note 1: Ensured by design.

2: $t_R = 5 \mu s$.

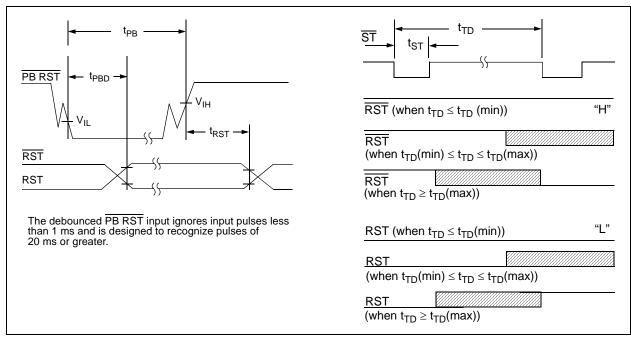


FIGURE 1-2: Push Button Reset and Watchdog Timer Reset Timing Waveforms.

AC CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise noted, $T_A = T_{MIN}$ to T_{MAX} ; $V_{CC} = +4.0 V$ to 5.5 V.						
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
PB RST Pulse Width	t _{PB}	20	_		ms	Note 1
PB RST Falling Edge Low to Reset Active	t _{PBD}	1	4	20	ms	
PB RST Rising Edge High to Reset Inactive	t _{RST}	250	610	1000	ms	
ST Pulse Width	t _{ST}	20	_	_	ns	
ST Time-out Period	t _{TD}	62.5	150	250	ms	TD Pin = 0V
		250	600	1000	ms	TD Pin = Open
		500	1200	2000	ms	TD Pin = V _{CC}

Note 1: PB RST must be held low for a minimum of 20 ms to ensure a Reset.

2.0 TYPICAL PERFORMANCE CURVES

Performance Graphs are not available.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLES

Pin	No.				
8-pin PDIP, SOIC	16-pin SOIC	Symbol	Pin Type	Buffer/ Driver Type	Function
1	2	PB RST		ST	Push Button Reset Input. Input for a Manual Reset Switch. This input debounces (ignores) pulses less than 1 ms in duration and is ensured to recognize inputs of 20 ms or greater. L = Manual Reset Switch is Active, Force RST/RST pins Active H = Manual Reset Switch is Inactive. State of RST/RST pins determined by other system conditions.
2	4	TD	-	ST	Time Delay Input. The voltage level on this input determines the Watchdog Timer Time-out period. TD = 0V \rightarrow t _{TD} = 150 ms TD = Open \rightarrow t _{TD} = 600 ms TD = V _{CC} \rightarrow t _{TD} = 1.2s
3	6	TOL	I	ST	Tolerance Input. TOL = GND, Max Voltage Trip Point (V_{CCTP}) = 4.75V (5% tolerance) TOL = V_{CC} , Max Voltage Trip Point (V_{CCTP}) = 4.5V (10% tolerance)
4	8	GND	_	Р	The ground reference for the device.
5	9	RST	0	Push Pull	Reset Output (Active-High) Goes active (High) if one of these conditions occurs: 1. If V _{CC} falls below the selected Reset voltage threshold. 2. If PBRST pin is forced low. 3. If ST pin is not strobed within the minimum selected time-out period. (see TD pin) 4. During power-up.
6	11	RST	0	Open Drain	Reset Output (Active-Low) Goes active (Low) if one of these conditions occurs: 1. If V _{CC} falls below the selected Reset voltage threshold. 2. If PBRST pin is forced low. 3. If ST pin is not strobed within the minimum selected time-out period. (see TD pin) 4. During power-up.
7	13	ST	I	ST	Strobe Input Input for Watchdog Timer. WDT period determined by state of TD pin Falling Edge → Resets Watchdog Timer counter (no time-out)
8	15	V _{CC}	_	Р	The positive supply (+5V) for the device.
_	1,3,5, 7,10,1 2,16	NC	_	_	No internal connection.

4.0 OPERATIONAL DESCRIPTION

4.1 Power Monitor

The TC1232 provides the function of warning the processor of a power failure. When V_{CC} is detected as being below the voltage levels defined by the TOL pin, the TC1232's comparator outputs the RST and RST signals to a logic level that warns the system of an out-of-tolerance power supply. The RST and \overline{RST} signals switch at a threshold value of 4.5V if TOL is tied to V_{CC} , and at a value of 4.75V if TOL is grounded. The RST and \overline{RST} signals are held active for a minimum of 250 ms to ensure that the power supply voltage has been stabilized.

Figure 4-1 shows the V_{CC} fall time.

Figure 4-2 shows the V_{CC} rise time.

Figure 4-3 shows the time from when the voltage trip point is detected to the Reset output pin going active.

Figure 4-4 shows the time from when the voltage trip point is exited to the Reset output pin going inactive.

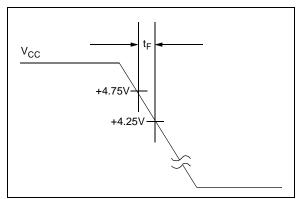


FIGURE 4-1: Power-Down Slew Rate.

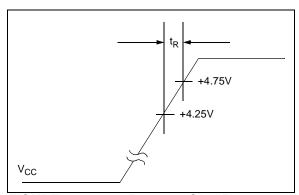


FIGURE 4-2: Power-up Slew Rate.

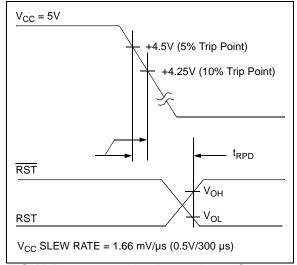


FIGURE 4-3: V_{CC} Detect Reset Output Delay (Power-Down).

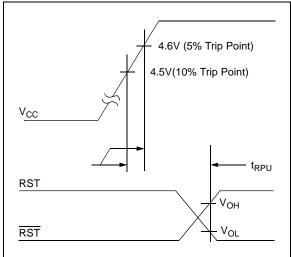


FIGURE 4-4: V_{CC} Detect Reset Output Delay (Power-Up).

4.2 Push Button Reset Input

The debounced manual Reset input (PB RST) manually forces the Reset outputs into their active states. Figure 4-5 shows a block diagram for using the TC1232 with a push button switch.

Once $\overline{\text{PB RST}}$ has been low for a time t_{PBD} (the push button delay time), the Reset outputs go active. The Reset outputs remain in their active states for a minimum of 250 ms after $\overline{\text{PB RST}}$ rises above V_{IH} . Figure 4-6 shows a waveform for the push button switch input and the Reset pins output.

A mechanical push button or active logic signal can drive the \overline{PB} RST input. The debounced input ignores input pulses less than 1 ms and recognizes pulses of 20 ms or greater. No external pull-up resistor is required because the \overline{PB} RST input has an internal pull-up to V_{CC} of approximately 100 μA .

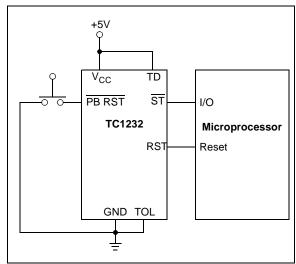
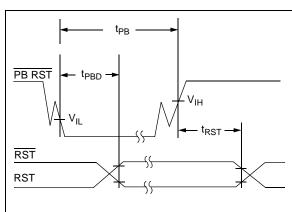


FIGURE 4-5: Push Button Reset and Watchdog Timer.



The debounced $\overline{\mbox{PB RST}}$ input ignores input pulses less than 1 ms and is designed to recognize pulses of 20 ms or greater.

FIGURE 4-6: Push Button Reset – PB RST Input.

4.3 Watchdog Timer

When the \overline{ST} input is not stimulated for a preset time period, the Watchdog Timer function forces RST and RST signals to the active state. The preset time period is determined by the \overline{TD} inputs to be 150 ms with TD connected to ground, 600 ms with TD floating or 1200 ms with TD connected to V_{CC} (typ.). The Watchdog Timer starts timing-out from the set time period as soon as RST and \overline{RST} are inactive. If a high-to-low transition occurs on the \overline{ST} input pin prior to time-out, the Watchdog Timer is reset and begins to time-out again. If the Watchdog Timer is allowed to time-out, the RST and \overline{RST} signals are driven to the active state for 250 ms, minimum (Figure 4-7).

The software routine that strobes \overline{ST} is critical. The code must be in a section of software that is executed frequently enough so the time between toggles is less than the Watchdog Time-out period. One common technique controls the microprocessor I/O line from two sections of the program. The software might set the I/O line high while operating in the Foreground mode and set it low while in the Background or Interrupt modes. If both modes do not execute correctly, the Watchdog Timer issues Reset pulses.

 t_{TD} is the maximum elapsed time between \overline{ST} high-to-low transitions (\overline{ST} is activated by falling edges only), which will keep the Watchdog Timer from forcing the Reset outputs active for a time of t_{RST} . t_{TD} is a function of the voltage at the TD pin, as tabulated below:

TABLE 4-1: WATCHDOG TIMER PERIODS

	t _{TD}			
Condition	Min.	Тур.	Max.	
TD pin = 0V	62.5 ms	150 ms	250 ms	
TD pin = Open	250 ms	600 ms	1000 ms	
TD pin = V _{CC}	500 ms	1200 ms	2000 ms	

Figure 4-7 shows a block diagram for using the TC1232 with a PIC^{\circledR} MCU and the Watchdog input.

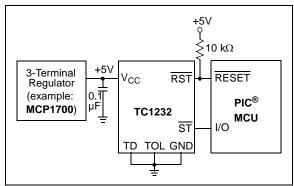


FIGURE 4-7: Watchdog Timer.

Figure 4-8 shows the expected Reset output pin waveforms depending on the period of the ST pin falling edge and the state of the TD input pin.

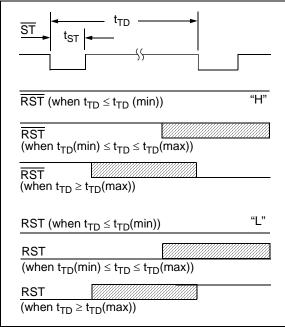


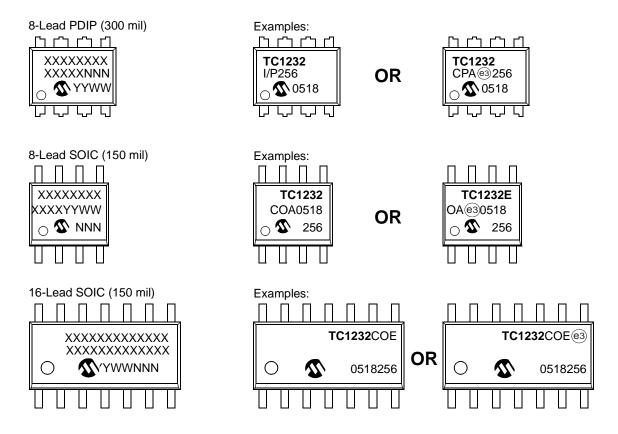
FIGURE 4-8: Strobe Input.

4.4 Supply Monitor Noise Sensitivity

The TC1232 is optimized for fast response to negative-going changes in $V_{DD}.$ Systems with an inordinate amount of electrical noise on V_{DD} (such as systems using relays) may require a 0.01 μF or 0.1 μF bypass capacitor to reduce detection sensitivity. This capacitor should be installed as close to the TC1232 as possible to keep the capacitor lead length short.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information



Legend: XX...X Customer-specific information
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code

© Pb-free JEDEC® designator for Matte Tin (Sn)

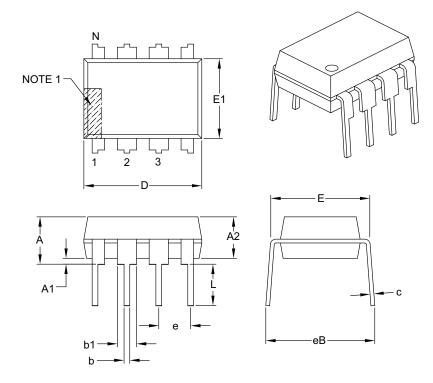
* This package is Pb-free. The Pb-free JEDEC designator (©3)
can be found on the outer packaging for this package.

In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

Note:

8-Lead Plastic Dual In-Line (PA) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES		
Dimer	nsion Limits	MIN	NOM	MAX
Number of Pins	N		8	
Pitch	е		.100 BSC	
Top to Seating Plane	Α	-	_	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	_
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	С	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	-	_	.430

Notes:

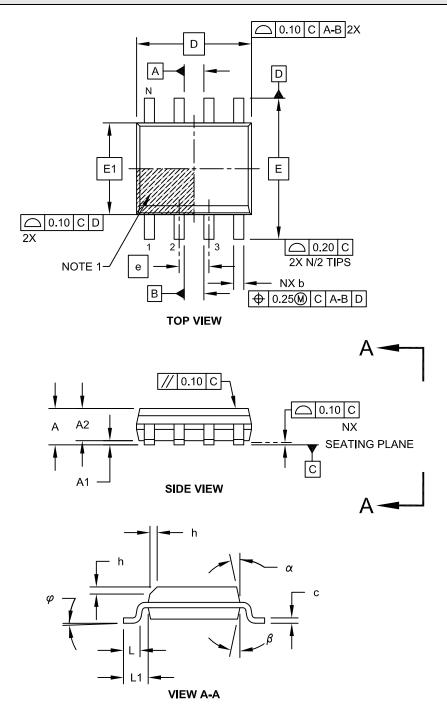
- 1. Pin 1 visual index feature may vary, but must be located with the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018B

8-Lead Plastic Small Outline (OA) - Narrow, 3.90 mm Body [SOIC]

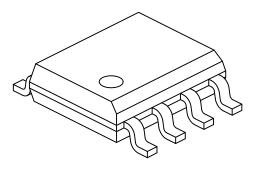
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing No. C04-057C Sheet 1 of 2 $\,$

8-Lead Plastic Small Outline (OA) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS				
Dimension	MIN	NOM	MAX		
Number of Pins	N		8		
Pitch	е		1.27 BSC		
Overall Height	Α	1	ı	1.75	
Molded Package Thickness	A2	1.25	ı	-	
Standoff §	A1	0.10	ı	0.25	
Overall Width	Е		6.00 BSC		
Molded Package Width	E1	3.90 BSC			
Overall Length	D		4.90 BSC		
Chamfer (Optional)	h	0.25	ı	0.50	
Foot Length	L	0.40	-	1.27	
Footprint	L1		1.04 REF		
Foot Angle	φ	0°	ı	8°	
Lead Thickness	С	0.17	-	0.25	
Lead Width	b	0.31	ı	0.51	
Mold Draft Angle Top	α	5°	-	15°	
Mold Draft Angle Bottom	β	5°	-	15°	

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M

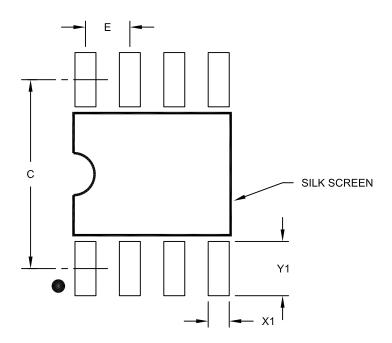
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-057C Sheet 2 of 2

8-Lead Plastic Small Outline (OA) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	Limits	MIN	MOM	MAX
Contact Pitch	Е		1.27 BSC	
Contact Pad Spacing	С		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

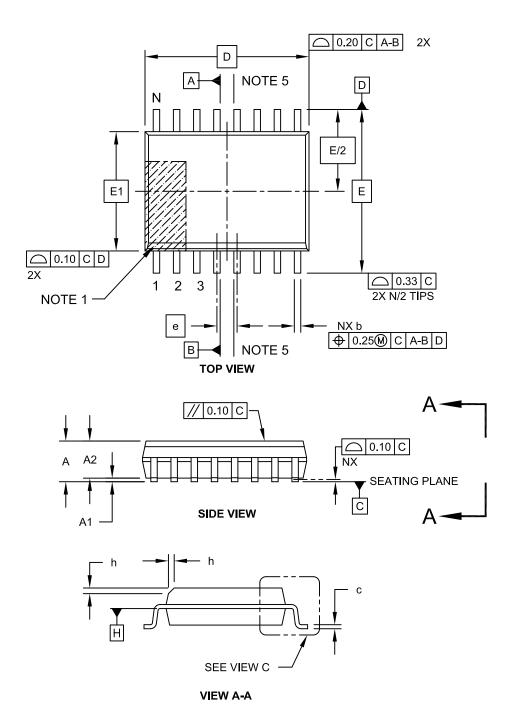
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

16-Lead Plastic Small Outline (OE) - Wide, 7.50 mm Body [SOIC]

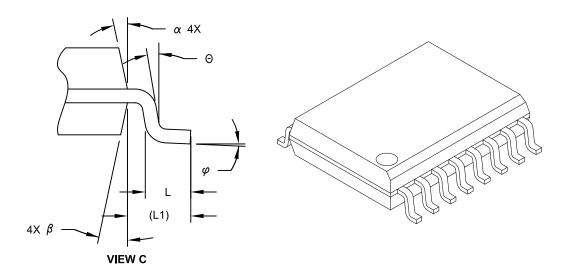
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-102C Sheet 1 of 2

16-Lead Plastic Small Outline (OE) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension Lin	MIN	NOM	MAX	
Number of Pins	N		16	
Pitch	е		1.27 BSC	
Overall Height	Α	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1	7.50 BSC		
Overall Length	D	10.30 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	i
Foot Angle	φ	0°	-	8°
Lead Thickness	С	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M

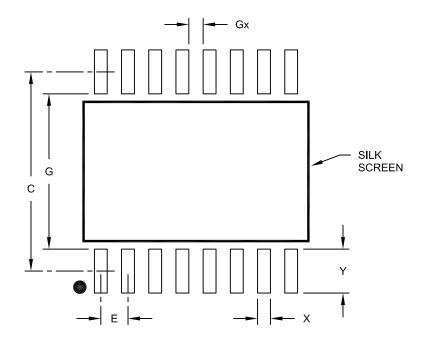
BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.

5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-102C Sheet 2 of 2

16-Lead Plastic Small Outline (OE) - Wide, 7.50 mm Body [SOIC] Land Pattern

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units			S
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	Е		1.27 BSC	
Contact Pad Spacing	С		9.30	
Contact Pad Width	Х			0.60
Contact Pad Length	Υ			2.05
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2102A

Т	~1	222
•	C I	ZJZ

NOTES:

APPENDIX A: REVISION HISTORY

Revision E (February 2014)

• Removed the "Preliminary" watermark.

Revision D (November 2012)

• Added a note to the package outline drawing.

Revision C (June 2005)

The following is the list of modifications:

- Since no data is given in Section 2.0 "Typical Performance Curves", "Preliminary" was added to the bottom of this document.
- 2. Corrected Operating Voltage in the Electrical Specifications.
- 3. General Data Sheet Enhancements.
- 4. Added Revision History Appendix Section.

Revision B (March 2003)

Not logged

Revision A (March 2002)

• Original Release of this Document.

TC1232

NOTES:

I

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

Device Temp	K /XX 	,	0°C to +70°C, 8L-SOIC 0°C to +70°C, 8L-SOIC, Tape and Reel
Device:	TC1232: Microprocessor Monitor	c) TC1232COE: d) TC1232COE713:	0°C to +70°C, 16L-SOIC 0°C to +70°C, 16L-SOIC Tape and Reel
Temperature Range:	C = 0°C to +70°C E = -40°C to +85°C	e) TC1232CPA: f) TC1232EOA:	0°C to +70°C, 8L-PDIP -40°C to +85°C, 8L-SOIC
Package:	PA = Plastic DIP (300 mil Body), 8-lead OA = Plastic SOIC, (150 mil Body), 8-lead OA713 = Plastic SOIC, (150 mil Body), 8-lead Tape and Reel OE = Plastic SOIC (300 mil Body), 16-lead OE713 = Plastic SOIC (300 mil Body), 16-lead Tape and Reel	g) TC1232EOA713: h) TC1232EOE:	8L-SOIC, Tape and Reel -40°C to +85°C,
		i) TC1232EOE713:	16L-SOIC -40°C to +85°C, 16L-SOIC, Tape and Reel
		j) TC1232EPA:	-40°C to +85°C, 8L-PDIP

Т	<u>'</u> ^ 1	222
•	し I	ZJZ

NOTES:

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV = ISO/TS 16949=

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MTP, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, SQI, Serial Quad I/O, Total Endurance, TSHARC, UniWinDriver, WiperLock, ZENA and Z-Scale are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

GestIC and ULPP are registered trademarks of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2002-2014, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

ISBN: 978-1-62077-944-6

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd.

Chandler, AZ 85224-6199 Tel: 480-792-7200

Fax: 480-792-7277 Technical Support:

http://www.microchip.com/ support

Web Address:

www.microchip.com

Atlanta

Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Cleveland

Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi. MI

Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Indianapolis Noblesville, IN

Tel: 317-773-8323 Fax: 317-773-5453

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110

Canada - Toronto Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong

Tel: 852-2401-1200 Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8569-7000 Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hangzhou

Tel: 86-571-2819-3187 Fax: 86-571-2819-3189

China - Hong Kong SAR

Tel: 852-2943-5100 Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8864-2200 Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-3019-1500

Japan - Osaka

Tel: 81-6-6152-7160 Fax: 81-6-6152-9310

Japan - Tokyo

Tel: 81-3-6880- 3770 Fax: 81-3-6880-3771

Korea - Daegu

Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-5778-366 Fax: 886-3-5770-955

Taiwan - Kaohsiung

Tel: 886-7-213-7830

Taiwan - Taipei

Tel: 886-2-2508-8600 Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Dusseldorf

Tel: 49-2129-3766400

Germany - Munich

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Pforzheim Tel: 49-7231-424750

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Venice

Tel: 39-049-7625286

Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Poland - Warsaw

Tel: 48-22-3325737

Spain - Madrid

Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Stockholm

Tel: 46-8-5090-4654 **UK - Wokingham**

Tel: 44-118-921-5800 Fax: 44-118-921-5820

10/28/13

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Microchip:

<u>TC1232COA713 TC1232EOA713 TC1232CPA TC1232COA TC1232COE TC1232EOE TC1232EOA TC123EOA TC123EOA TC123EOA TC123EOA TC123EOA TC12A TC123EOA TC123EOA TC123EOA TC123EOA TC</u>